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The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

**Continuity of document content**

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

**Continuity of ordering part numbers**

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.

144 Lead Thin Plastic Quad Flatpack  
20 X 20 X 1.4mm

The drawing includes the following views and dimensions:


- Top View:** Shows the package footprint with overall dimensions of  $22.00 \pm 0.100$  SQ and  $20.00 \pm 0.050$  SQ. Pin locations are marked with numbers 1, 108, 109, 144, 36, 37, 72, and 73. Lead thickness is  $0.22 \pm 0.05$  mm, and the typical lead height is 0.50 TYP.
- Bottom View (Exposed Pad Option):** Shows a central  $5 \times 5$  mm PAD and the same pin locations as the top view.
- Side View:** Shows the package height of  $1.40 \pm 0.05$  mm. It includes a SEATING PLANE, a 0.08 mm fillet, a 0.20 mm maximum gap, and a 1.60 mm maximum dimension. The lead angle is  $12^\circ \pm 1^\circ$  (8X).
- DETAIL A:** A cross-sectional detail of the lead and pad assembly. It specifies a STAND-OFF of 0.05 mm minimum to 0.15 mm maximum, a lead angle of  $0^\circ$  minimum, a pad radius of  $R 0.08$  mm minimum to  $0.20$  mm maximum, a gauge plane at 0.25 mm, a lead thickness of 0.20 mm minimum, and a total width of  $0.60 \pm 0.15$  mm. A 1.00 mm reference dimension is also shown.

Package Weight ~ 1.3 grams  
JEDEC Outline MS-026


(DIMENSIONS ARE IN MILLIMETERS)

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SPEC NO. 51-85047						REV *E	
SCALE						SHEET 1	OF 2

Package Weight ~ 1.3 grams  
JEDEC Outline MS-026

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<div>TITLE</div> <div>PACKAGE OUTLINE, 144LD TQFP (20X20X1.4 MM) A144SA</div>			
<div>SPEC NO.</div> <div>51-85047</div>			<div>REV</div> <div>*E</div>
SCALE		SHEET 1	OF 2

Rev	ECN No.	Orig. of change	Description of Change
**	567	—	NEW RELEASE
*A	49396	—	DEL. NOTES, CHG. TITLE
*B	1213246	—	ADD BOTTM VIEW FOR EXPOSED PAD OPTION
*C	2780710	TZWTMP3	CHANGE TEMPLATE, CHANGE TITLE FROM 144LD TQFP (20X20X1.4) PKG. OUTLINE TO PACKAGE OUTLINE, 144LD TQFP (20X20X1.4 MM) A144SA
*D	3310710	QADTMP1	NO CHANGE. SUNSET REVIEW.
*E	4613335	ROWI	SUNSET REVIEW, CHANGED DRAWING TEMPLATE.

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TITLE PACKAGE OUTLINE, 144LD TQFP (20X20X1.4 MM) A144SA	
SPEC NO. 51-85047	REV *E
SCALE	SHEET 2 OF 2

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PACKAGE  
CODE(S)

A144SA